



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE4263G		<b>Issued</b>		28. August 2013		
<b>MA#</b>		MA000835082						
<b>Package</b>		PG-DSO-20-35		<b>Weight*</b>		478.22 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.136	0.66	0.66	6558	6558
leadframe	inorganic material	phosphorus	7723-14-0	0.036	0.01		75	
	non noble metal	zinc	7440-66-6	0.143	0.03		299	
	non noble metal	iron	7439-89-6	2.862	0.60		5984	
wire	non noble metal	copper	7440-50-8	116.197	24.30	24.94	242978	249336
	noble metal	gold	7440-57-5	0.363	0.08	0.08	759	759
	encapsulation	organic material	carbon black	1333-86-4	0.700	0.15		1463
encapsulation	plastics	epoxy resin	-	32.192	6.73		67315	
	inorganic material	silicondioxide	60676-86-0	317.017	66.27	73.15	662910	731688
leadfinish	non noble metal	tin	7440-31-5	2.746	0.57	0.57	5742	5742
plating	noble metal	silver	7440-22-4	1.177	0.25	0.25	2461	2461
glue	plastics	epoxy resin	-	0.413	0.09		864	
	noble metal	silver	7440-22-4	1.239	0.26	0.35	2592	3456
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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